

IN THE CLAIMS

1. (Canceled)

2. (Currently Amended) A glide test system combination comprising:
a glide test system apparatus including a glide head having
a glide body including a leading edge, a trailing edge
and a contoured disc facing surface having a raised
bearing surface elevated from a recessed bearing
surface; and
at least one thermal transducer formed on the raised bearing
surface having a surface portion extending along a
portion of the raised bearing surface to form a glide
interface to detect asperities and a thickness portion
intersecting the surface portion extending along the
portion of the raised bearing surface to form a glide
interface to detect asperities and the thickness
portion forming a contour profile of the contoured disc
facing surface of the glide body relative to the raised
bearing surface and the recessed bearing surface.

3. (Canceled)

4. (Currently Amended) The glide head of claim 228 wherein the
raised bearing surface includes opposed side rails oriented along
a length of the glide body and the at least one thermal transducer
is formed along a portion of a length of at least one of the
opposed side rails.

5. (Previously Amended) The glide head of claim 4 wherein each of
the opposed side rails includes at least one thermal transducer

6. (Currently Amended) The glide head of claim 228 wherein the at |

least one thermal transducer is in electrical contact with electrically conductive pads proximate to the trailing edge of the glide body.

7. (Previously Amended) The glide head of claim 6 including conductive strips conductively coupled to the at least one thermal transducer and the conductive pads to provide an electrical contact between the thermal transducer and the pads.

8. (Canceled)

9. (Currently Amended) The glide head of claim 228 wherein the at least one thermal transducer extends along at least half of a length distance between the leading edge and the trailing edge of the glide body.

10. (Currently Amended) The glide head of claim 228 wherein the at least one thermal transducer extends substantially from the leading edge to the trailing edge of the glide body.

11. (Currently Amended) The glide head of claim 228 and comprising a plurality of thermal transducers.

12. (Previously Amended) The glide head of claim 11 wherein the plurality of thermal transducers comprise a first thermal transducer and a second thermal transducer and the first and second thermal transducers share a common electrical ground.

13. (Previously Amended) The glide head of claim 11 wherein the plurality of thermal transducers are spaced along the raised bearing surface and the glide head further comprises electrically conductive strips in electrical contact with the plurality of

thermal transducers, the strips being formed on a recessed bearing surface offset from the raised bearing surface.

14. (Currently Amended) The glide head of claim 228 further comprising a piezoelectric transducer.

15. (Canceled)

16. (Previously Amended) A method of fabricating a glide head comprising:

fabricating an air bearing surface on a disc facing surface of the glide head including a raised bearing surface and a recessed bearing surface; and
depositing a thermal transducer on the raised bearing surface to form a surface portion providing a glide interface to detect asperities and a thickness portion forming a contour profile of the disc facing surface relative to the recessed bearing surface and the raised bearing surface.

17. (Canceled)

18. (Previously Amended) A method of fabricating a glide head from a wafer comprising;

slicing a plurality of glide bodies from the wafer; and
depositing thermal transducers on the plurality of glide bodies sliced from the wafer.

19. (Canceled)

20. (Original) The method of claim 16 wherein the deposition is performed using a thin film deposition technique.

21. (Previously Amended) The method of claim 18 and further comprising:

fabricating an air bearing on the plurality of glide bodies sliced from the wafer including a raised bearing surface and a recessed bearing surface prior to depositing the thermal transducers; and
depositing the thermal transducers on the raised bearing surfaces of the plurality of glide bodies sliced from the wafer.

22. (Canceled)

23. (Currently Amended) The glide head of claim 228 including a plurality of spaced thermal transducers spaced along a length of the glide body between the leading edge and the trailing edge of the glide body.

24. (Currently Amended) The glide head of claim 228 including a protective layer deposited on the at least one thermal transducer.

25. (Previously Amended) A glide head comprising:

a glide body including a leading edge, a trailing edge and a raised bearing surface and a recessed bearing surface; and
asperity detection means on the glide body for detecting asperities on a disc surface.

26. (Previously Amended) The method of claim 16 wherein the step of fabricating the raised bearing surface and the recessed surface and the deposition of the thermal transducer is performed on a surface of a wafer prior to slicing a plurality of glide heads from the wafer.

27. (Original) A head comprising:

a body portion including a leading edge, a trailing edge and a raised bearing surface extending along a portion of a length of the body portion between the leading edge and the trailing edge; and

at least one thermal transducer formed on the raised bearing surface

at least one conductive pad on the trailing edge of the body portion and a conductive strip electrically connecting the at least one bond pad and the at least one thermal transducer along the raised bearing surface.

[Please add new claims 28 - 29.]

28. (New) A glide head comprising:

a glide body including a leading edge, a trailing edge and a contoured disc facing surface having a raised bearing surface elevated from a recessed bearing surface; and

at least one thermal transducer formed on the raised bearing surface having a surface portion extending along the raised bearing surface to form a glide interface to detect asperities and a thickness portion intersecting the surface portion and forming a contour profile of the contoured disc facing surface relative to the raised bearing surface and the recessed bearing surface.

29. (New) The method of claim 16 wherein the air bearing surface is fabricated prior to the step of depositing the thermal transducer on the raised bearing surface.